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Collana	Advanced Materials Research, , 1662-8985 ; ; Volume 1038
Disciplina	621.367
Soggetti	Molded interconnect devices Three-dimensional display systems
Lingua di pubblicazione	Inglese
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Livello bibliografico	Monografia
Note generali	Description based upon print version of record.
Nota di bibliografia	Includes bibliographical references at the end of each chapters and index.
Nota di contenuto	11th International Congress Molded Interconnect Devices - Scientific Proceedings; Preface and Committees; Table of Contents; Chapter 1: Development and Prototyping; Method for the Identification and Comparison of Alternative Process Chains Focusing on Economics Efficiency Analysis during the Conceptual Design of Mechatronic Integrated Devices; Novel Approach for the Implementation of 3D-MID Compatible Routing Functionalities into Computer-Aided Design Tools; Optimized Process Sequences for Prototyping of Molded Interconnect Devices; Integration of Functional Circuits into FDM Parts Chapter 2: Printing Technologies Printing of Functional Structures on Molded 3D Devices; Electrical Functionalization of Thermoplastics by Combining Plasmadust Coating and Aerosol Jet Printing; Production of Miniaturized Sensor Structures on Polymer Substrates Using Inkjet Printing; Progress in the Manufacturing of Molded Interconnected Devices by 3D Microcontact Printing; Chapter 3: Materials and Manufacturing; Characterization of Electromagnetic Properties of MID

Materials for High Frequency Applications up to 67 GHz
Novel Laser Induced Metallization for Three Dimensional Molded
Interconnect Device Applications by Spray Method
Experimental Investigation of Laser Sintering of Conductive Adhesive for Functional
Prototypes Produced by Embedding Stereolithography; MID Fabricated
by Ultrasonic Processing; Usage of Industrial Robots as Flexible
Handling Devices Supporting the Process of Three Dimensional
Conductive Pattern Generation; Chapter 4: Manufacturing Processes;
Study of MID Technologies for Automotive Lighting and Light Signaling
Devices; Chapter 5: Assembly Technologies and Inspection
Design and Solder Process Optimization in MID Technology for High
Power Applications
Chapter 6: Quality and Reliability; Hot Pin Pull
Method - New Test Procedure for the Adhesion Measurement for 3D-
MID; Keywords Index; Authors Index

Sommario/riassunto

Collection of selected, peer reviewed papers from the 11 th
International Congress Molded Interconnect Devices (MID 2014),
September 24-25, 2014, Nuremberg / Fuerth, Germany. The 16 papers
are grouped as follows: Chapter 1: Development and Prototyping,
Chapter 2: Printing Technologies, Chapter 3: Materials and
Manufacturing, Chapter 4: Manufacturing Processes, Chapter 5:
Assembly Technologies and Inspection, Chapter 6: Quality and
Reliability.
